

Inverting Charge Pump Voltage Doublers with Active High Shutdown

Features

- Small 8-Pin MSOP Package
- Operates from 1.8V to 5.5V
- 120 Ohms (typ) Output Resistance
- 99% Voltage Conversion Efficiency
- Only 3 External Capacitors Required
- Power-Saving Shutdown Mode
- Low Active Supply Current
 - 95µA (typ) for TC1682
 - 225µA (typ) for TC1683
 - 700µA (typ) for TC1684
- Fully Compatible with 1.8V Logic Systems

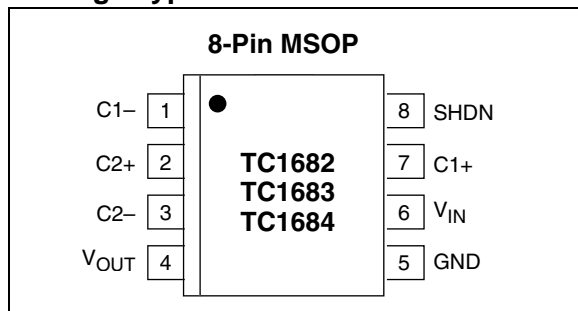
Applications

- LCD Panel Bias
- Cellular Phones PA Bias
- Pagers
- PDAs, Portable Data Loggers
- Battery-Powered Devices

Device Selection Table

| Part Number | Package | Osc. Freq. (kHz) | Operating Temp. Range |
|-------------|------------|------------------|-----------------------|
| TC1682EUA | 8-Pin MSOP | 12 | -40°C to +85°C |
| TC1683EUA | 8-Pin MSOP | 35 | -40°C to +85°C |
| TC1684EUA | 8-Pin MSOP | 125 | -40°C to +85°C |

Package Type



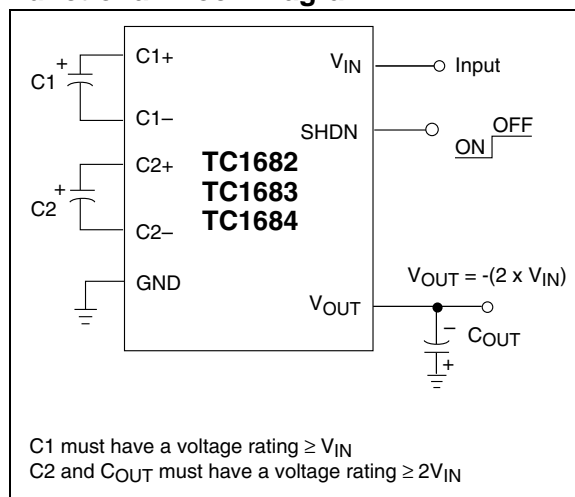
General Description

The TC1682/TC1683/TC1684 are CMOS charge pump converters that provide an inverted doubled output from a single positive supply. An on-board oscillator provides the clock and only three external capacitors are required for full circuit implementation. Switching frequencies are 12kHz for the TC1682, 35kHz for the TC1683, and 125kHz for the TC1684. When the SHDN pin is held at a logic high, the device goes into a very low power mode of operation consuming less than 1µA (typ) of supply current.

Low output source impedance (typically 120Ω), provides output current up to 10mA. The TC1682/TC1683/TC1684 feature a 1.8V to 5.5V operating voltage range and high efficiency, which make them an ideal choice for a wide variety of applications requiring a negative doubled voltage derived from a single positive supply (for example: generation of -7.2V from a +3.6V lithium cell or -10V generated from a +5V logic supply).

The minimum external part count, small physical size and shutdown mode feature make this family of products useful for a wide variety of negative bias power supply applications.

Functional Block Diagram



TC1682/TC1683/TC1684

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Input Voltage (V_{IN} to GND)..... +6.0V, -0.3V
Output Voltage (V_{OUT} to GND)..... -12.0V, +0.3V
Current at V_{OUT} Pin.....20mA
Short-Circuit Duration V_{OUT} to GNDIndefinite
Power Dissipation ($T_A \leq 70^\circ\text{C}$)
 8-Pin MSOP320mW
Operating Temperature Range..... -40°C to +85°C
Storage Temperature (Unbiased) -65°C to +150°C

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

TC1682/TC1683/TC1684 ELECTRICAL SPECIFICATIONS

| Electrical Characteristics: $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $V_{IN} = +5\text{V}$, $C1 = C2 = 3.3\mu\text{F}$ (TC1682), $C1 = C2 = 1\mu\text{F}$ (TC1683), $C1 = C2 = 0.33\mu\text{F}$ (TC1684), SHDN = GND, Typical values are at $T_A = +25^\circ\text{C}$ | | | | | | | |
|--|---------------------------------|-------------------|--------------------|---------------------|-----------------|----------------------------|---|
| Symbol | Parameter | Min | Typ | Max | Units | Device | Test Conditions |
| I_{DD} | Supply Current | — | 95 225 700 | 160 480 1500 | μA | TC1682 TC1683 TC1684 | |
| I_{SHDN} | Shutdown Supply Current | — | 0.5 | 2 | μA | All | SHDN = $V_{IN} = +5\text{V}$ |
| V_{MIN} | Minimum Supply Voltage | 1.8 | — | — | V | All | $R_{LOAD} = 1\text{k}\Omega$ |
| V_{MAX} | Maximum Supply Voltage | — | — | 5.5 | V | All | $R_{LOAD} = 1\text{k}\Omega$ |
| F_{OSC} | Oscillator Frequency | 8.4 24.5 65 | 12 35 125 | 15.6 45.5 170 | kHz | TC1682 TC1683 TC1684 | |
| V_{IH} | SHDN Input Logic High | 1.4 | — | — | V | All | $V_{IN} = V_{MIN}$ to V_{MAX} |
| V_{IL} | SHDN Input Logic Low | — | — | 0.4 | V | All | $V_{IN} = V_{MIN}$ to V_{MAX} |
| V_{EFF} | Voltage Conversion Efficiency | 95 | 99 | — | % | All | $R_{LOAD} = \infty$ |
| R_{OUT} | Output Resistance | — | 120 | 170 | Ω | All | $I_{LOAD} = 0.5\text{mA}$ to 10mA (Note 1) |
| T_{WK} | Wake-up Time From Shutdown Mode | — | 1800 600 200 | — — — | μsec | TC1682 TC1683 TC1684 | $R_{LOAD} = 2\text{k}\Omega$ |

Note 1: Capacitor contribution is approximately 20% of the output impedance ($ESR = 1/\text{pump frequency} \times \text{capacitance}$).

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

| Pin No. (8-Pin MSOP) | Symbol | Description |
|-------------------------|------------------|---|
| 1 | C1– | C1 commutation capacitor negative terminal. |
| 2 | C2+ | C2 commutation capacitor positive terminal. |
| 3 | C2– | C2 commutation capacitor negative terminal. |
| 4 | V _{OUT} | Doubling inverting charge pump output ($-2 \times V_{IN}$). |
| 5 | GND | Ground. |
| 6 | V _{IN} | Positive power supply input. |
| 7 | C1+ | C1 commutation capacitor positive terminal. |
| 8 | SHDN | Shutdown input (active high). |

TC1682/TC1683/TC1684

3.0 DETAILED DESCRIPTION

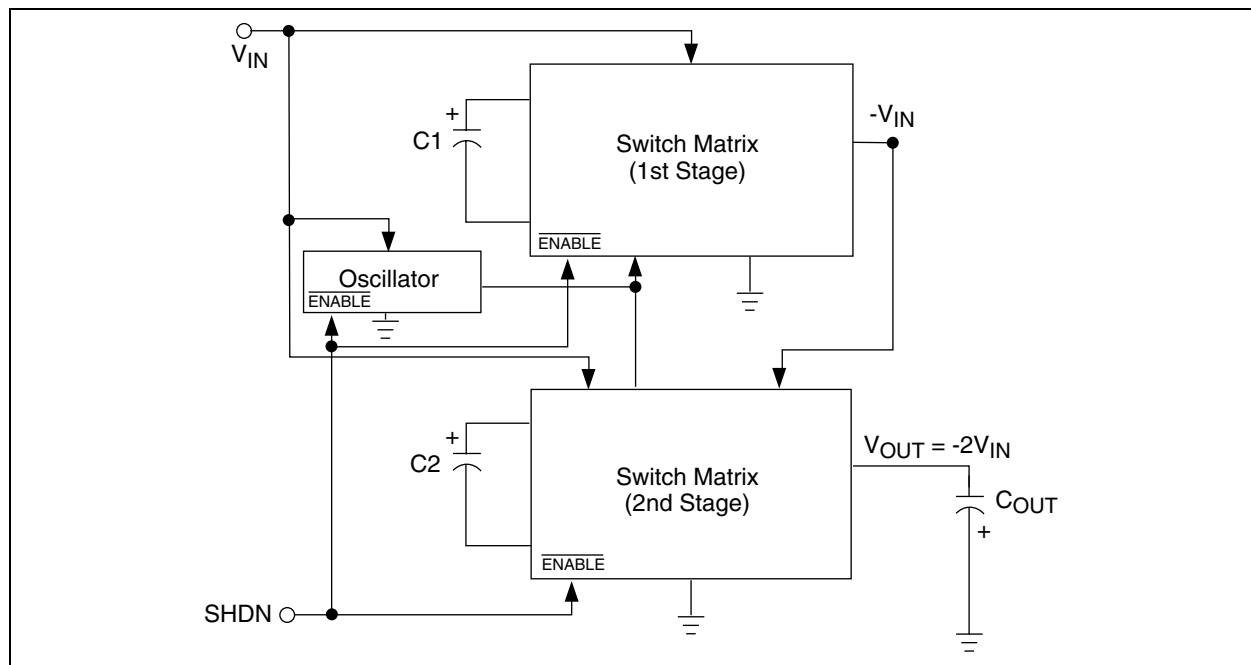
The TC1682/TC1683/TC1684 inverting charge pump converters perform a $-2\times$ multiplication of the voltage applied to the V_{IN} pin. Conversion is performed using two *synchronous* switching matrices and three external capacitors. When the shutdown input is held at a logic high, the device goes into a very low power mode of operation consuming less than $1\mu A$ of supply current.

Figure 3-1 is a block diagram representation of the TC1682/TC1683/TC1684 architecture. The first switching stage inverts the voltage present at V_{IN} and the second stage uses the ' $-V_{IN}$ ' output generated from the first stage to produce the ' $-2\times$ ' output function from the second stage switching matrix.

Each device contains an on-board oscillator that synchronously controls the operation of the charge pump switching matrices. The TC1682 synchronously switches at 12kHz, the TC1683 synchronously switches at 35kHz, and the TC1684 synchronously switches at 125kHz. The different oscillator frequencies for this device family allow the user to trade-off capacitor size versus supply current. Faster oscillators can use smaller external capacitors, but will consume more supply current (see Section 1.0 Electrical Characteristics).

When the shutdown input is in a high state, the oscillator and both switch matrices are powered off placing the TC1682/TC1683/TC1684 in the shutdown mode. When the V_{IN} supply input is powered from an external battery, the shutdown mode minimizes power consumption, which in turn will extend the life of the battery.

FIGURE 3-1: TC1682/TC1683/TC1684 ARCHITECTURE



4.0 APPLICATIONS INFORMATION

4.1 Output Voltage Considerations

The TC1682/TC1683/TC1684 perform inverting voltage conversions but do not provide any type of regulation. The output voltage will droop in a linear manner with respect to the output load current. The value of the equivalent output resistance is approximately 120Ω nominal at +25°C and $V_{IN} = +5V$. In this particular case, the output is approximately -10V at very light loads and will droop according to the equation below:

$$V_{DROOP} = I_{OUT} \times R_{OUT}$$

4.2 Capacitor Selection

In order to maintain the lowest output resistance and output ripple voltage, it is recommended that low ESR capacitors be used. Additionally, larger values of C1 and C2 will lower the output resistance and larger values of C_{OUT} will reduce output ripple.

Note: For proper charge pump operation, C1 must have a voltage rating greater than or equal to V_{IN} , while C2 and C_{OUT} must have a voltage rating greater than or equal to $2V_{IN}$.

Table 4-1 shows various values of C1/C2 and the corresponding output resistance values for $V_{IN} = 5V$ @ +25°C.

Table 4-2 shows the output voltage ripple for various values of C_{OUT} (again assuming $V_{IN} = 5V$ @ +25°C). The V_{RIPPLE} values assume a 1mA output load current and a 0.1Ω ESR_{COUT} .

TABLE 4-1: OUTPUT RESISTANCE VS. C1/C2 (ESR = 0.1Ω)

| C1, C2 (μF) | TC1682 $R_{OUT}(\Omega)$ | TC1683 $R_{OUT}(\Omega)$ | TC1684 $R_{OUT}(\Omega)$ |
|-------------|--------------------------|--------------------------|--------------------------|
| 0.33 | 633 | 184 | 120 |
| 1 | 262 | 120 | 102 |
| 3.3 | 120 | 95 | 84 |

TABLE 4-2: OUTPUT VOLTAGE RIPPLE VS. C_{OUT2} (ESR = 0.1Ω) $I_{OUT} = 1mA$

| C_{OUT} (μF) | TC1682 V_{RIPPLE} (mV) | TC1683 V_{RIPPLE} (mV) | TC1684 V_{RIPPLE} (mV) |
|----------------|--------------------------|--------------------------|--------------------------|
| 0.33 | 192 | 60 | 27 |
| 1 | 63 | 21 | 16 |
| 3.3 | 17 | 8 | 7 |

4.3 Input Supply Bypassing

The V_{IN} input should be capacitively bypassed to reduce AC impedance and minimize noise effects due to the switching internal to the device. It is recommended that a large value capacitor (at least equal to C1) be connected from V_{IN} to GND for optimal circuit performance.

4.4 Shutdown Input

The TC1682/TC1683/TC1684 is enabled when SHDN is low, and disabled when SHDN is high. This input cannot be allowed to float. (If SHDN is not required, see the TC2682/TC2683/TC2684 data sheet.) The SHDN input should be limited to 0.3V above V_{IN} .

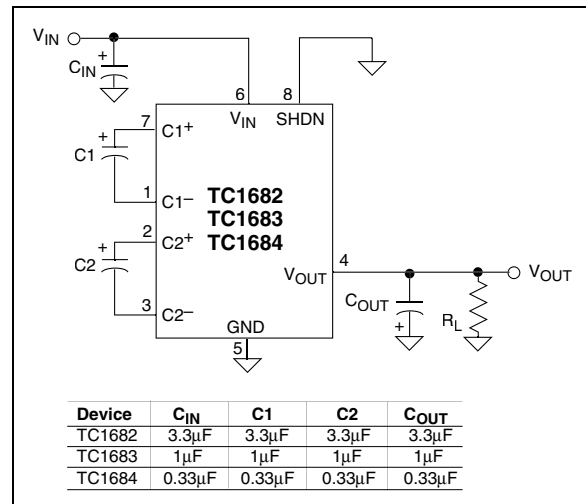
4.5 Inverting Voltage Doubler

The most common application for the TC1682/TC1683/TC1684 devices is the inverting voltage doubler (Figure 4-1). This application uses three external capacitors: C1, C2 and C_{OUT} .

Note: A power supply bypass capacitor is recommended.

The output is equal to $-2V_{IN}$ plus any voltage drops due to loading. Refer to Table 4-1 and Table 4-2 for capacitor selection guidelines.

FIGURE 4-1: INVERTING VOLTAGE DOUBLER TEST CIRCUIT



4.6 Layout Considerations

As with any switching power supply circuit, good layout practice is recommended. Mount components as close together as possible to minimize stray inductance and capacitance. Also use a large ground plane to minimize noise leakage into other circuitry.

TC1682/TC1683/TC1684

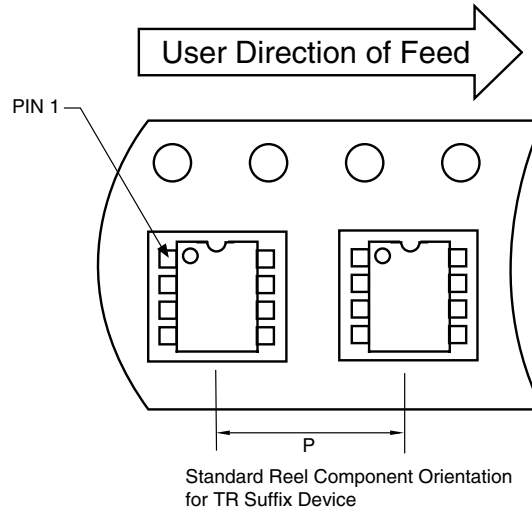
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

Package marking data not available at this time.

5.2 Taping Form

Component Taping Orientation for 8-Pin MSOP Devices

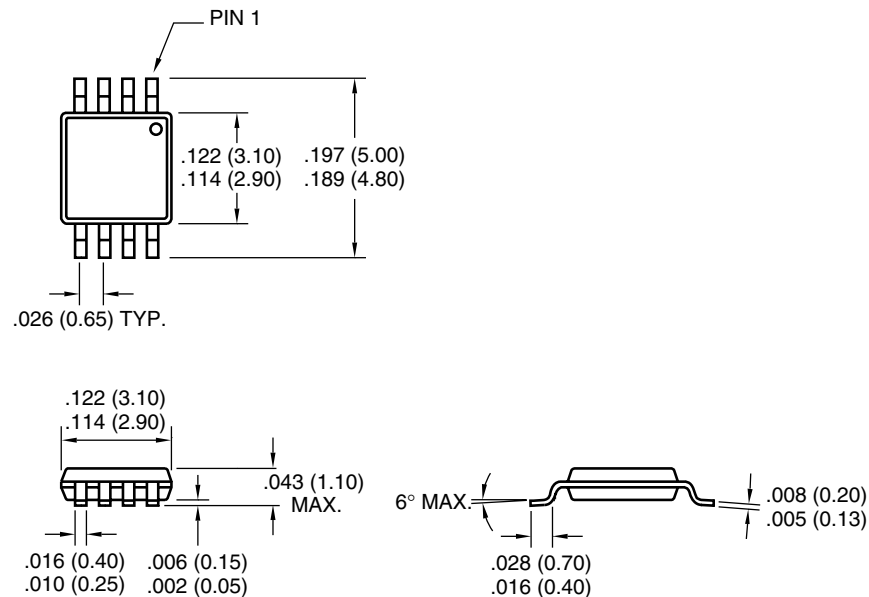


Carrier Tape, Number of Components Per Reel and Reel Size

| Package | Carrier Width (W) | Pitch (P) | Part Per Full Reel | Reel Size |
|------------|-------------------|-----------|--------------------|-----------|
| 8-Pin MSOP | 12 mm | 8 mm | 2500 | 13 in |

5.3 Package Dimensions

8-Pin MSOP



Dimensions: inches (mm)

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

New Customer Notification System

Register on our web site (www.microchip.com/cn) to receive the most current information on our products.

TC1682/TC1683/TC1684

NOTES:

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any intellectual property rights.

Trademarks


The Microchip name and logo, the Microchip logo, FilterLab, KEELOQ, microID, MPLAB, PIC, PICmicro, PICMASTER, PICSTART, PRO MATE, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

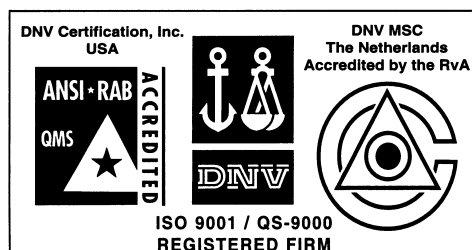
dsPIC, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, microPort, Migratable Memory, MPASM, MPLIB, MPLINK, MPSIM, MXDEV, PICC, PICDEM, PICDEM.net, rfPIC, Select Mode and Total Endurance are trademarks of Microchip Technology Incorporated in the U.S.A.

Serialized Quick Turn Programming (SQTP) is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2002, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.



Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999 and Mountain View, California in March 2002. The Company's quality system processes and procedures are QS-9000 compliant for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, non-volatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001 certified.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200 Fax: 480-792-7277
Technical Support: 480-792-7627
Web Address: <http://www.microchip.com>

Rocky Mountain

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7966 Fax: 480-792-7456

Atlanta

500 Sugar Mill Road, Suite 200B
Atlanta, GA 30350
Tel: 770-640-0034 Fax: 770-640-0307

Boston

2 Lan Drive, Suite 120
Westford, MA 01886
Tel: 978-692-3848 Fax: 978-692-3821

Chicago

333 Pierce Road, Suite 180
Itasca, IL 60143
Tel: 630-285-0071 Fax: 630-285-0075

Dallas

4570 Westgrove Drive, Suite 160
Addison, TX 75001
Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Tri-Atria Office Building
32255 Northwestern Highway, Suite 190
Farmington Hills, MI 48334
Tel: 248-538-2250 Fax: 248-538-2260

Kokomo

2767 S. Albright Road
Kokomo, Indiana 46902
Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles

18201 Von Karman, Suite 1090
Irvine, CA 92612
Tel: 949-263-1888 Fax: 949-263-1338

New York

150 Motor Parkway, Suite 202
Hauppauge, NY 11788
Tel: 631-273-5305 Fax: 631-273-5335

San Jose

Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408-436-7950 Fax: 408-436-7955

Toronto

6285 Northam Drive, Suite 108
Mississauga, Ontario L4V 1X5, Canada
Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Australia

Microchip Technology Australia Pty Ltd
Suite 22, 41 Rawson Street
Epping 2121, NSW
Australia
Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Microchip Technology Consulting (Shanghai)
Co., Ltd., Beijing Liaison Office
Unit 915
Bei Hai Wan Tai Bldg.
No. 6 Chaoyangmen Beidajie
Beijing, 100027, No. China
Tel: 86-10-85282100 Fax: 86-10-85282104

China - Chengdu

Microchip Technology Consulting (Shanghai)
Co., Ltd., Chengdu Liaison Office
Rm. 2401, 24th Floor,
Ming Xing Financial Tower
No. 88 TIDU Street
Chengdu 610016, China
Tel: 86-28-6766200 Fax: 86-28-6766599

China - Fuzhou

Microchip Technology Consulting (Shanghai)
Co., Ltd., Fuzhou Liaison Office
Unit 28F, World Trade Plaza
No. 71 Wusi Road
Fuzhou 350001, China
Tel: 86-591-7503506 Fax: 86-591-7503521

China - Shanghai

Microchip Technology Consulting (Shanghai)
Co., Ltd.
Room 701, Bldg. B
Far East International Plaza
No. 317 Xian Xia Road
Shanghai, 200051
Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

China - Shenzhen

Microchip Technology Consulting (Shanghai)
Co., Ltd., Shenzhen Liaison Office
Rm. 1315, 13/F, Shenzhen Kerry Centre,
Renminnan Lu
Shenzhen 518001, China
Tel: 86-755-2350361 Fax: 86-755-2366086

Hong Kong

Microchip Technology Hongkong Ltd.
Unit 901-6, Tower 2, Metroplaza
223 Hing Fong Road
Kwai Fong, N.T., Hong Kong
Tel: 852-2401-1200 Fax: 852-2401-3431

India

Microchip Technology Inc.
India Liaison Office
Divyasree Chambers
1 Floor, Wing A (A3/A4)
No. 11, O'Shaugnessey Road
Bangalore, 560 025, India
Tel: 91-80-2290061 Fax: 91-80-2290062

Japan

Microchip Technology Japan K.K.
Benex S-1 6F
3-18-20, Shinyokohama
Kohoku-Ku, Yokohama-shi
Kanagawa, 222-0033, Japan
Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea

Microchip Technology Korea
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku
Seoul, Korea 135-882
Tel: 82-2-554-7200 Fax: 82-2-558-5934

Singapore

Microchip Technology Singapore Pte Ltd.
200 Middle Road
#07-02 Prime Centre
Singapore, 188980
Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan

Microchip Technology Taiwan
11F-3, No. 207
Tung Hua North Road
Taipei, 105, Taiwan
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

EUROPE

Denmark

Microchip Technology Nordic ApS
Regus Business Centre
Lautrup høj 1-3
Ballerup DK-2750 Denmark
Tel: 45 4420 9895 Fax: 45 4420 9910

France

Microchip Technology SARL
Parc d'Activite du Moulin de Massy
43 Rue du Saule Trapu
Batiment A - 1er Etage
91300 Massy, France
Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany

Microchip Technology GmbH
Gustav-Heinemann Ring 125
D-81739 Munich, Germany
Tel: 49-89-627-144 0 Fax: 49-89-627-144-44

Italy

Microchip Technology SRL
Centro Direzionale Colleoni
Palazzo Taurus 1 V. Le Colleoni 1
20041 Agrate Brianza
Milan, Italy
Tel: 39-039-65791-1 Fax: 39-039-6899883

United Kingdom

Arizona Microchip Technology Ltd.
505 Eskdale Road
Winnersh Triangle
Wokingham
Berkshire, England RG41 5TU
Tel: 44 118 921 5869 Fax: 44-118 921-5820

03/01/02

